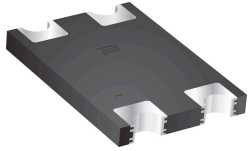


# MATERIAL DECLARATION SHEET



<b>Material Number</b>	<b>CD-MBL2xxSL</b>			
<b>Product Line</b>	<b>Semiconductor Products</b>			
<b>Compliance Date</b>	<b>2016/4/07</b>			
<b>RoHS Compliant</b>	<b>Yes</b>	<b>MSL</b>	<b>1</b>	

No.	Construction Element(subpart)	Homogeneous Material	Material weight [mg]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	FRP	Metal	74.13	Continuous filament glass fibers	65997-17-3	43.00	28.98	67.4
				Copper foil	7440-50-8	14.00	9.44	
				Non-Hazardous cured resin	Proprietary	43.00	28.98	
2	Epoxy	Plastic	25.20	Silicon Dioxide	7631-86-9	55.00	12.595	22.9
				Epoxy resin	9003-36-5	45.00	10.305	
3	Solder Cream	Metal	1.52	Lead <sup>2</sup>	7439-92-1	88.00	1.216	1.4
				Tin	7440-31-5	10.00	0.138	
				Silver	7440-22-4	2.00	0.028	
4	Dice	Metal	6.95	Silicon	7440-21-3	35.77	2.26	6.3
				Nickel	7440-02-0	0.70	0.044	
				Lead-containing glass <sup>3</sup>	7439-92-1	63.51	4.013	
				Gold	7440-57-5	0.02	0.001	
5	Terminal Plating	Metal	2.20	Tin	7440-31-5	100	2.000	2.0
			Total weight	110.0				

**This Document was updated on: 2016/4/07**

**Important remarks:**

# MATERIAL DECLARATION SHEET

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1. It is the responsibility of the user to verify they are accessing the latest version.
2. Excepted for RoHS 7(a) Lead in high melting temperature type solders
3. Excepted for RoHS 7(c)-I Lead in a glass or ceramic matrix compound.